



NOTE.3:

1. ALL EXPOSED METALLIZED AREA SHALL BE GOLD PLATED 80 MICRO INCHES MIN. THICKNESS OVER NICKEL PLATING UNLESS OTHERWISE SPECIFIED IN PURCHASE ORDER.
2. NO PIN CONNECTED TO SEAL AREA AND DIE ATTACH AREA (ZERO GROUND)
3. SEAL AREA TO EXTEND TO WITHIN .001 OF THE OUTSIDE EDGE & WITHIN .005 OF THE INSIDE EDGE.
4. LEAD TO LEAD LEAKAGE MUST NOT EXCEED 5 NANO AMPS AT 100 V.D.C.
5. LEAD RESISTANCE : 0.4 Ω MAX.

				NAME CA LEAD CHIP CARRIER		TOLERANCES: UNLESS OTHERWISE SPECIFIED: ±1%		DATE	DESIGN
				SCALE 10/1	MATERIAL KYOCERA A-140		APPROVED 8/78		REVISED
CHANGER				DATE		N.L.T. ±.005		DRAWN 8/78	
				DRAWN		KYOCERA CORPORATION		KYOTO JAPAN	
				CHECKED		DWG-6 PB-34094		83.4.15	
				APPROVED					